# **DTC123E** series

NPN 100mA 50V Digital Transistor (Bias Resistor Built-in Transistor)

Parameter	Value	
V <sub>CC</sub>	50V	
I <sub>C(MAX.)</sub>	100mA	
R <sub>1</sub>	2.2kΩ	
R <sub>2</sub>	2.2kΩ	

## Features

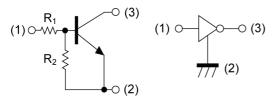
- 1) Built-In Biasing Resistors,  $R_1 = R_2 = 2.2k\Omega$
- Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see inner circuit).
- 3) Only the on/off conditions need to be set for operation, making the circuit design easy.
- 4) Complementary PNP Types: DTA123E series

## Application

INVERTER, INTERFACE, DRIVER

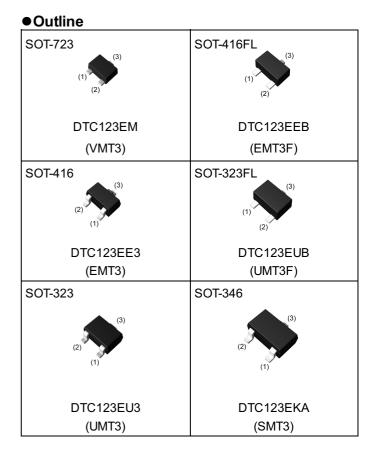
## Inner circuit

DTC123EM/ DTC123EEB/ DTC123EUB

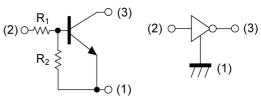


(1) IN (BASE)(2) GND (EMITTER)(3) OUT (COLLECTOR)

## Packaging specifications



# DTC123EE3/ DTC123EU3/ DTC123EKA



(1) GND (EMITTER)
(2) IN (BASE)
(3) OUT (COLLECTOR)

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Quantity (pcs)	Marking
DTC123EM	SOT-723	1212	T2L	180	8	8000	22
DTC123EEB	SOT-416FL	1616	TL	180	8	3000	22
DTC123EE3	SOT-416	1616	TL	180	8	3000	22
DTC123EUB	SOT-323FL	2021	TL	180	8	3000	22
DTC123EU3	SOT-323	2021	T106	180	8	3000	22
DTC123EKA	SOT-346	2928	T146	180	8	3000	22

## • Absolute maximum ratings (T<sub>a</sub> = 25°C)

F	Symbol	Values	Unit	
Supply voltage		V <sub>CC</sub>	50	V
Input voltage		V <sub>IN</sub>	-10 to 12	V
Output current		Ι <sub>ο</sub>	100	mA
Collector current			100	mA
	DTC123EM		150	
	DTC123EEB		150	
Dower discipation	DTC123EE3		150	ma)///
Power dissipation	DTC123EUB	FD-	200	— mW
	DTC123EU3		200	
	DTC123EKA		200	
Junction temperature		Tj	150	°C
Range of storage tempera	ature	T <sub>stg</sub>	-55 to +150	°C

## •Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Current al	Conditions	Values			1 1	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
	V <sub>I(off)</sub>	V <sub>CC</sub> = 5V, I <sub>O</sub> = 100µA	-	- 0.5		N	
Input voltage	V <sub>I(on)</sub>	V <sub>O</sub> = 0.3V, I <sub>O</sub> = 20mA	3.0	-	-	V	
Output voltage	V <sub>O(on)</sub>	I <sub>O</sub> = 10mA, I <sub>I</sub> = 0.5mA	-	100	300	mV	
Input current	I <sub>I</sub>	V <sub>1</sub> = 5V	-	-	3.8	mA	
Output current	I <sub>O(off)</sub>	$V_{CC} = 50V, V_{I} = 0V$	-	-	500	nA	
DC current gain	GI	V <sub>O</sub> = 5V, I <sub>O</sub> = 20mA	20	-	-	-	
Input resistance	R <sub>1</sub>	-	1.54	2.2	2.86	kΩ	
Resistance ratio	R <sub>2</sub> /R <sub>1</sub>	-	0.8	1.0	1.2	-	
Transition frequency	f <sub>T</sub> *1	V <sub>CE</sub> = 10V, I <sub>E</sub> = -5mA, f = 100MHz	-	250	-	MHz	

\*1 Characteristics of built-in transistor

\*2 Each terminal mounted on a reference land.



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INPUT VOLTAGE : V<sub>(on)</sub> [V]

3.0

# •Electrical characteristic curves (T<sub>a</sub> =25°C)

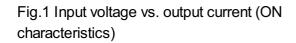


Fig.2 Output current vs. input voltage (OFF characteristics)

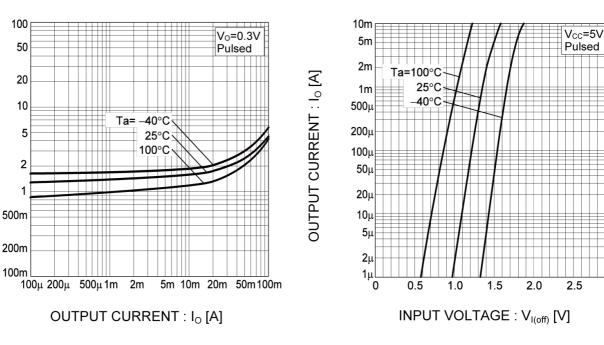


Fig.3 Output current vs. output voltage

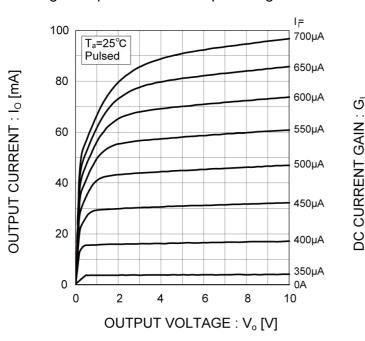
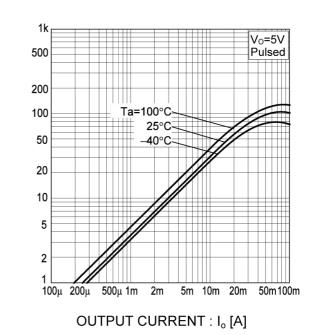
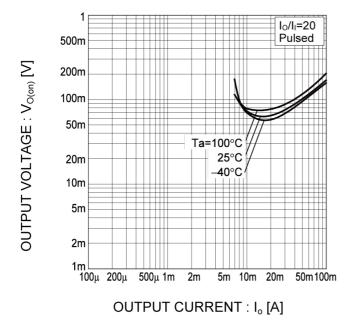


Fig.4 DC current gain vs. output current





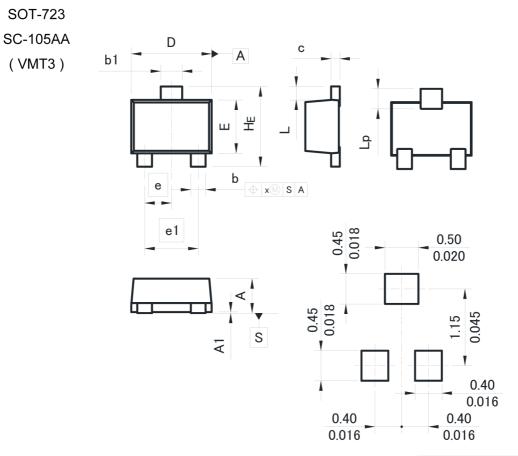
# ●Electrical characteristic curves (T<sub>a</sub> =25°C)



## Fig.5 Output voltage vs. output current







Soldering footprint Unit: (mm inches)

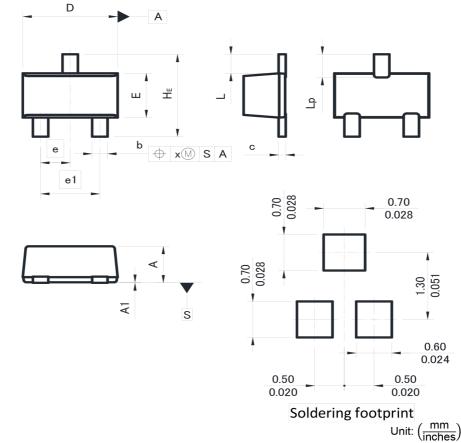
	Millimeters		Inc	nes
DIM	Min.	Max.	Min.	Max.
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
С	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
е	0.40		0.016	
e1	3.0	30	0.0	31
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
Х	_	0.10	-	0.004



SOT-416FL

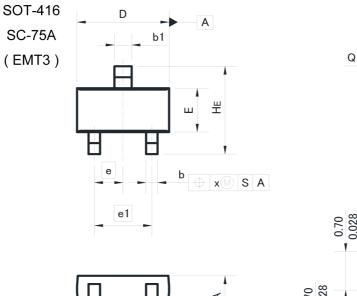
SC-89

(EMT3F)



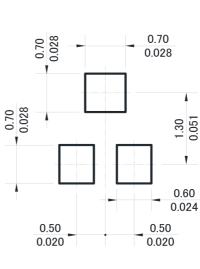
DIM	Millim	neters	Inc	hes
	Min.	Max.	Min.	Max.
А	0.60	0.90	0.024	0.035
A1	0.00	0.10	0.000	0.004
b	0.21	0.36	0.008	0.014
С	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	0.76	0.96	0.030	0.038
е	0.5	50	0.020	
e1	0.90	1.10	0.035	0.043
HE	1.50	1.70	0.059	0.067
L	0.37		0.0	15
Lp	0.35	0.55	0.014	0.022
Х	_	0.10	_	0.004





A1

S



С

 $\frac{\text{Soldering footprint}}{\text{Unit:}} \left(\frac{\text{mm}}{\text{inches}}\right)$ 

DIM	Millimeters		Inc	hes
	Min.	Max.	Min.	Max.
Α	0.60	0.90	0.024	0.035
A1	0.00	0.10	0.000	0.004
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
е	0.5	50	0.020	
e1	1.00		0.0	39
HE	1.40	1.80	0.055	0.071
L	0.10	-	0.004	-
Q	0.05	0.25	0.002	0.010
X	-	0.10	-	0.004

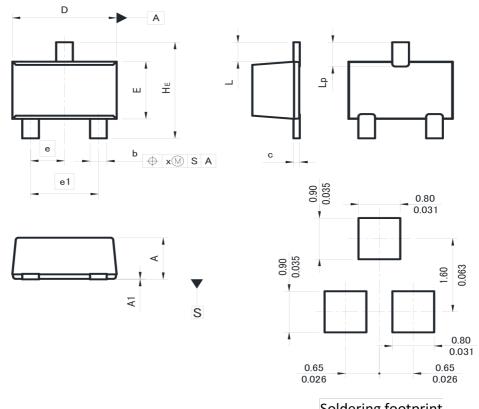




SOT-323FL

SC-85

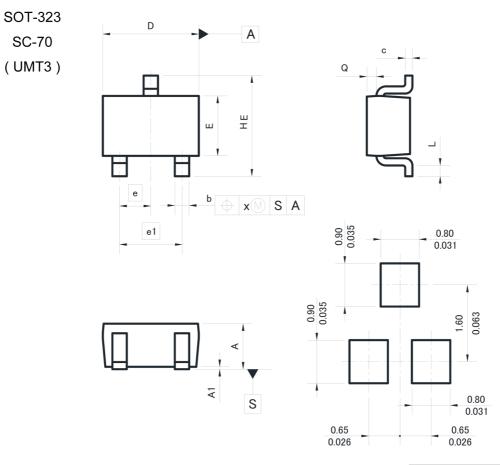
(UMT3F)



Soldering footprint Unit:  $\binom{mm}{inches}$ 

	Millim	neters	Inc	hes
DIM	Min.	Max.	Min.	Max.
Α	0.80	1.10	0.031	0.043
A1	0.00	0.10	0.000	0.004
b	0.27	0.42	0.011	0.017
С	0.08	0.18	0.003	0.007
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.6	65	0.026	
e1	1.20	1.40	0.047	0.055
HE	2.00	2.20	0.079	0.087
L	0.43		0.0	17
Lp	0.43	0.63	0.017	0.025
Х	_	0.10	_	0.004

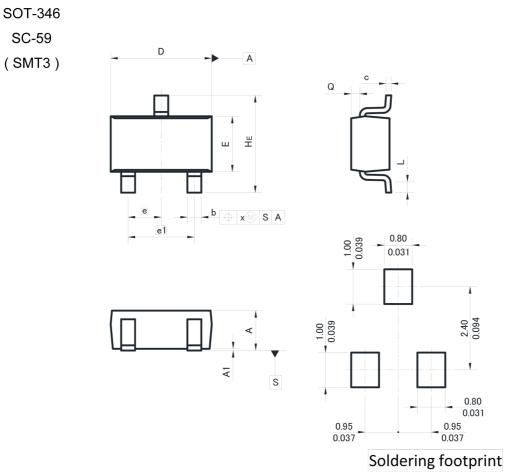




Soldering footprint Unit:  $\binom{mm}{inches}$ 

DIM	Millim	ieters	Inc	hes
	Min.	Max.	Min.	Max.
A	0.80	1.10	0.031	0.043
A1	0.00	0.10	0.000	0.004
b	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.6	65	0.026	
e1	1.3	30	0.0	51
HE	2.00	2.20	0.079	0.087
L	0.10	-	0.004	-
Q	0.10	0.30	0.004	0.012
х	-	0.10	-	0.004





Unit:  $\left(\frac{mm}{inches}\right)$ 

DIM	Millimeters		Inc	hes
	Min.	Max.	Min.	Max.
A	1.00	1.40	0.039	0.055
A1	0.00	0.10	0.000	0.004
b	0.35	0.50	0.014	0.020
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.95		0.037	
e1	1.9	90	0.075	
HE	2.60	3.00	0.102	0.118
L	0.30	0.60	0.012	0.024
Q	0.20	0.50	0.008	0.020
х	_	0.10	_	0.004



# Notice

#### Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (<sup>Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications
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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSI	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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